

Abstract

Provided is an electronic parts mount apparatus for taking out semiconductor chips from a semiconductor wafer held on a wafer hold section by a transfer head comprising a plurality of suction nozzles and transporting and mounting the semiconductor chips to and on a board has a parts recognition camera disposed in a manner that it can advance to and retreat from the wafer hold section for picking up an image of the semiconductor wafer. Also provided is a method including a parts mounting step for mounting a plurality of semiconductor chips on the board by the transfer head and an image picking up step for picking up a plurality of semiconductor chips to be next taken out by the parts recognition camera which are performed concurrently.